

Leepoxy Plastics, Inc.

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TECHNICAL BULLETIN LEECURE B-1310

Description

LEECURE B-1310 is a moderately reactive member of Leepoxy's proprietary liquid BF₃ epoxy curing agent family. When mixed with a standard Bisphenol A epoxy resin, LEECURE B-1310 provides a rapid cure at modest temperatures, assuming little or no heat sink effect. LEECURE B-1310's balance of pot life and reactivity makes it practical to dispense via meter-mix equipment or dual cartridge guns while maintaining high production throughput.

LEECURE B-1310 is compatible with Bisphenol A, Bisphenol F, flexible, cycloaliphatic, novolac, and other multifunctional epoxy resins. Cured systems offer exceptional chemical and heat resistance, tensile strength and electrical properties. The excellent physical properties of LEECURE B-1310 cured systems can be enhanced through the judicious choice of appropriate dry non-alkaline fillers. In unfilled systems, fracture, impact, and thermal shock resistance can be significantly improved through the incorporation of flexibilized resins or toughening agents. Leepoxy's proprietary 23-135 CTBN adduct is one such toughening agent.

TYPICAL PROPERTIES	
Appearance	Brown liquid
Viscosity @ 25°C, cps	14,700
Density, pounds/gallon	9.4
Shelf life, months	12

Handling and Mixing

Keep LEECURE B-1310 containers tightly sealed at all times. Use of dry nitrogen is recommended to protect partial containers from moisture contamination. The epoxy resin, fillers, and any other ingredients to be mixed should be moisture-free as well. Avoid alkaline fillers such as calcium carbonate. Fillers such as silica, barytes, glass, graphite, clays, and others that have a pH of 7 or lower are recommended. Mix very thoroughly in a dry mix vessel. No special equipment is necessary, but entrapment of excessive air bubbles should be avoided. Exposure to humidity in the air should be minimized from the time of mix until the product is ultimately heat cured because prolonged exposure to humidity may harm the reactivity, physical properties, and surface appearance of a LEECURE B-1310 cured system.

Curing Conditions

Epoxy compounds containing LEECURE B-1310 should be cured so as to control the effects of the exothermic reaction. The optimum time and temperature will depend on the particular formulation and the mass of compound. Longer cure schedules may be needed when curing thin sections or where the epoxy is adjacent to a mass of material that will act as a heat sink. The recommended minimum bondline cure temperature is 65°C. Generally, the higher the cure temperature, the better the heat resistance and physical properties of the cured systems.

TYPICAL PERFORMANCE	
Glass Transition Temperature, °C	134
Tensile Strength, psi	4,000
Tensile Modulus, psi	480,000
Tensile Elongation, %	4.0
Hardness, Shore D	90
Dielectric Constant, 1 mHz @ 25°C	3.9
Dissipation Factor, 1 mHz @ 25°C	0.018

Additives, modifiers, and diluents used in formulating epoxy compounds incorporating LEECURE B-1310 may have a marked effect not only on the cure rate but also the final properties of the cured system. Diluents, fillers, and flexibilizers will generally increase pot life, gel time, and cure time.

TYPICAL HANDLING PROPERTIES	
Mix Ratio ¹ , phr	8 – 12
Gel time @ 25°C, 11 g, minutes	20
Work Life @ 25°C, static mixer, minutes	40
Cure Time @ 65°C, 3/16 inch bead,	
Green Strength, minutes	2 – 4
Full Cure, minutes	5

1 Mix ratio with Bisphenol A Resin (EEW=189)